



<b>ENVIRONMENTAL AND PACKAGE TESTING DATA FOR SOT-223 (HVM)</b>					
<b>STRESS</b>	<b>SAMPLE SIZE</b>	<b>DEVICE HR./CYC</b>	<b>CONDITION</b>	<b>TOTAL FAILS</b>	<b>FAIL PERCENTAGE</b>
BOND INT	60	45 000	200 °C + N2	0	0.00
HAST	1200	120 000	130 °C, 85 % RH	0	0.00
Power Cycle	320	4 800 000	DELTA T <sub>j</sub> = 100 °C	0	0.00
Pressure Pot	1120	107 520	121°, 15 PSIG	0	0.00
Solder DUNK	200	600	260°, 10 s	0	0.00
Solderability	60	60	883 M2003	0	0.00
Temp. Cycle	1200	1 186 560	-55 °C to 150 °C	0	0.00